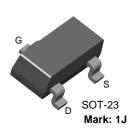


SEMICONDUCTOR®

MMBT2369

NPN Switching Transistor

- This device is designed for high speed saturated switching at collector currents of 10mA to 100mA.
- Sourced from process 21.



MMBT2369

Absolute Maximum Ratings* $T_a=25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Ratings	Units	
V _{CEO}	Collector-Emitter Voltage	15	V	
V _{CBO}	Collector-Base Voltage	40	V	
V _{EBO}	Emitter-Base Voltage	4.5	V	
l _C	Collector Current - Continuous	200	mA	
T _J , T _{STG}	Operating and Storage Junction Temperature Range	-55 ~ 150	°C	

* This ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

NOTES:

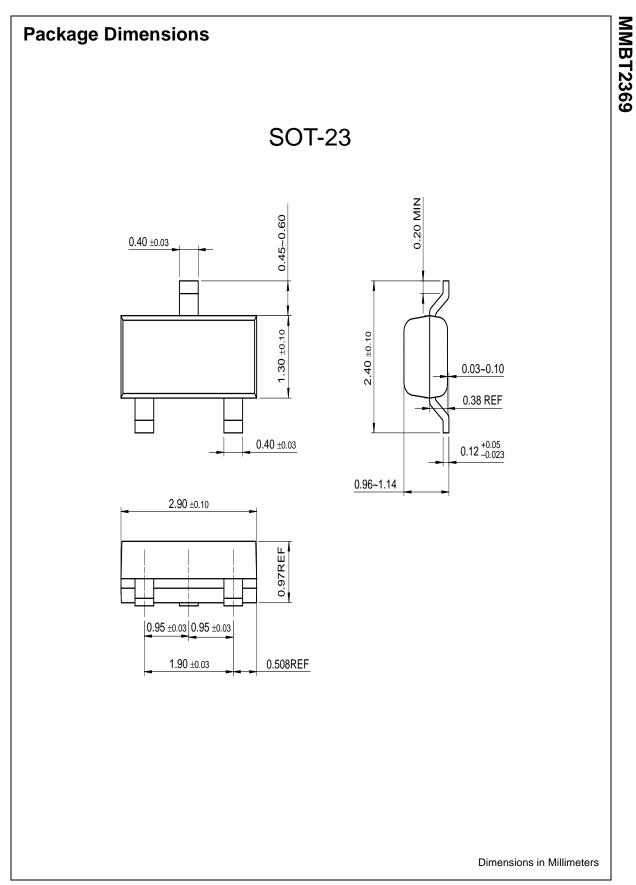
1) These rating are based on a maximum junction temperature of 150 degrees C.
2) These are steady limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Electrical Characteristics T_a=25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Max.	Units
Off Charac	cteristics				
V _{(BR)CEO}	Collector-Emitter Breakdown Voltage *	$I_{\rm C} = 10 {\rm mA}, I_{\rm B} = 0$	15		V
V _{(BR)CES}	Collector-Emitter Breakdown Voltage	$I_{C} = 10\mu A, V_{BE} = 0$	40		V
V _{(BR)CBO}	Collector-Base Breakdown Voltage	$I_{C} = 10\mu A, I_{E} = 0$	40		V
V _{(BR)EBO}	Emitter-Base Breakdown Voltage	$I_{E} = 10\mu A, I_{C} = 0$	4.5		V
I _{CBO}	Collector Cutoff Current	$V_{CB} = 20V, I_{E} = 0$		0.4	μA
		$V_{CB} = 20V, I_E = 0, T_a = 125^{\circ}C$		30	μA
On Charac	cteristics				
h _{FE}	DC Current Gain *	I _C = 10mA, V _{CE} = 1.0V	40	120	
		I _C = 100mA, V _{CE} = 2.0V	20		
V _{CE(sat)}	Collector-Emitter Saturation Voltage *	I _C = 10mA, I _B = 1.0mA		0.25	V
V _{BE(sat)}	Base-Emitter Saturation Voltage	I _C = 10mA, I _B = 1.0mA	0.7	0.85	V
	nal Characteristics	-			
C _{obo}	Output Capacitance	$V_{CB} = 5.0V, I_E = 0, f = 1.0MHz$		4.0	pF
C _{ibo}	Input Capacitance	$V_{EB} = 0.5V, I_{C} = 0, f = 1.0MHz$		5.0	pF
h _{fe}	Small -Signal Current Gain	I_C = 10mA, V_{CE} = 10V, R_G = 2.0k Ω , f = 100MHz	5.0		
Switching	Characteristics				
t _s	Storage Time	$I_{B1} = I_{B2} = I_C = 10 \text{mA}$		13	ns
t _{on}	Turn-On Time	V _{CC} = 3.0V, I _C = 10mA, I _{B1} = 3.0mA		12	ns
t _{off}	Turn-Off Time	$V_{CC} = 3.0V, I_{C} = 10mA, I_{B1} = 3.0mA, I_{B2} = 1.5mA$		18	ns

	onal action Strug T _a =25 C unless otherwise hote	u	Thermal Characteristics T _a =25°C unless otherwise noted			
Symbol	Parameter	Max.	Units			
P _D	Total Device Dissipation	350	mW			
	Derate above 25°C	2.8	mW/°C			
R _{0JC}	Thermal Resistance, Junction to Case	125	°C/W			
⋜ _{θJC} ⋜ _{θJA}	Thermal Resistance, Junction to Ambient	357	°C/W			

MMBT2369



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FACT™	ImpliedDisconnect™	OCXPro™	RapidConnect™	UHC™
Across the board	. Around the world.™	OPTOLOGIC [®]	SILENT SWITCHER [®]	UltraFET [®]
The Power France	chise [®]	OPTOPLANAR™	SMART START™	VCX™
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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
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